



VMDSEMI

**VTTL050R15BNA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
500V	1.45Ω@10V	5A

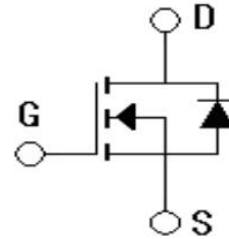
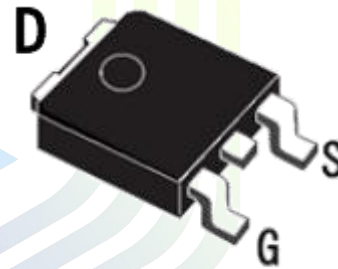


Figure 1 Symbol of VTTL050R15BNA

## Features

- Fast Switching
- Low Gate Charge
- Low Crss
- Improved dv/dt capability
- 100% UIS Tested
- RoHS product

## Package Type



**TO-252**

## Application

- High frequency switching mode power supply
- Electronic ballast
- UPS

Figure 2 Package Type of VTTL050R15BNA

## Ordering Information

Product Name	Package
VTTL050R15BNA	TO-252

**Absolute Maximum Ratings** ( $T_C=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	500	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current $T_C=25\text{ }^\circ\text{C}$	$I_D$	5	A
Continuous Drain Current $T_C=100\text{ }^\circ\text{C}$		3.16	
Pulsed Drain Current <sup>Note1</sup>	$I_{DM}$	20	
Avalanche Current <sup>Note1</sup>	$I_{AS}$	5	
Single Pulsed Avalanche Energy <sup>Note2</sup>	$E_{AS}$	305	mJ
Repetitive Pulsed Avalanche Energy <sup>Note1</sup>	$E_{AR}$	12.15	mJ
Peak Diode Recovery $dv/dt$ <sup>Note3</sup>	$dv/dt$	4.5	V/ns
Total Power Dissipation $T_C=25\text{ }^\circ\text{C}$	$P_D$	121	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Maximum Lead Temperature for Soldering Purposes	$T_L$	300	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$		62.5		$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.028		$^\circ\text{C/W}$

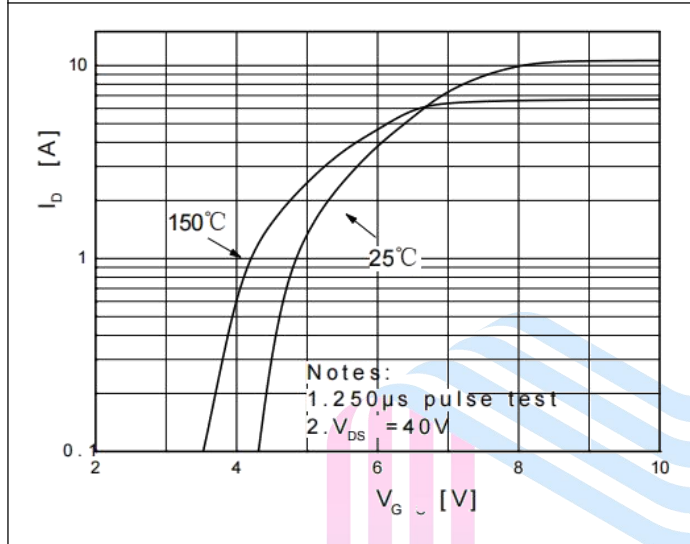
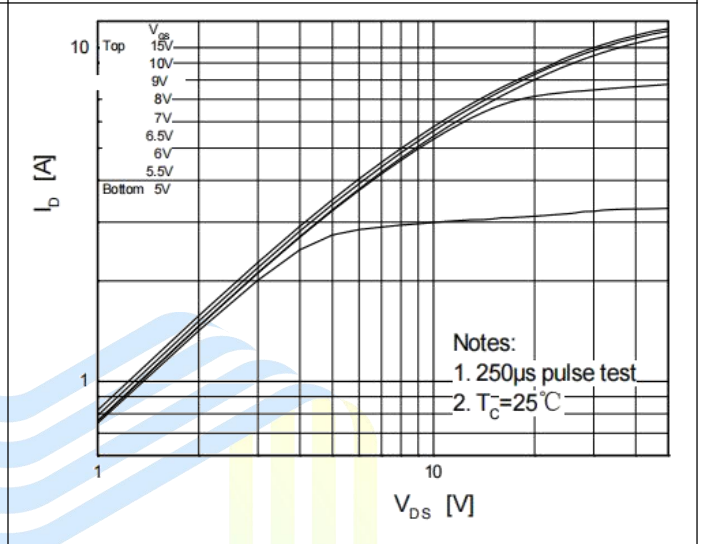
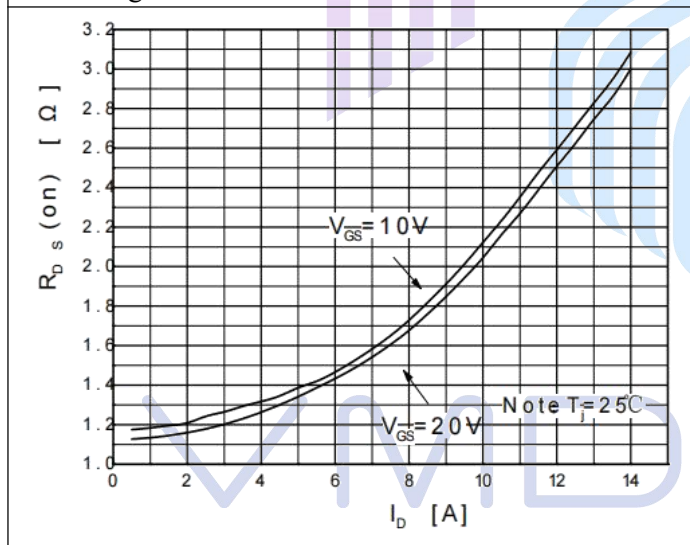
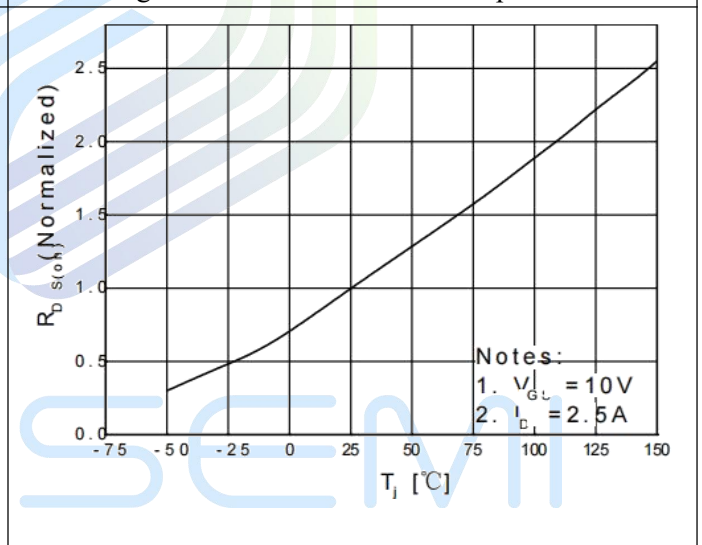


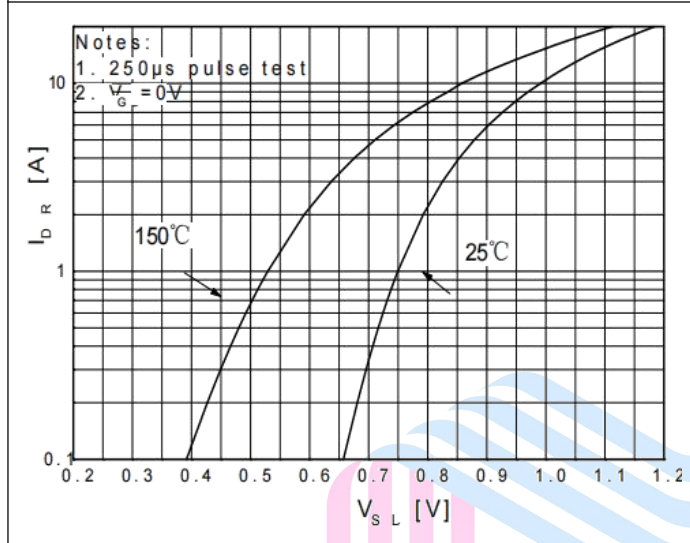
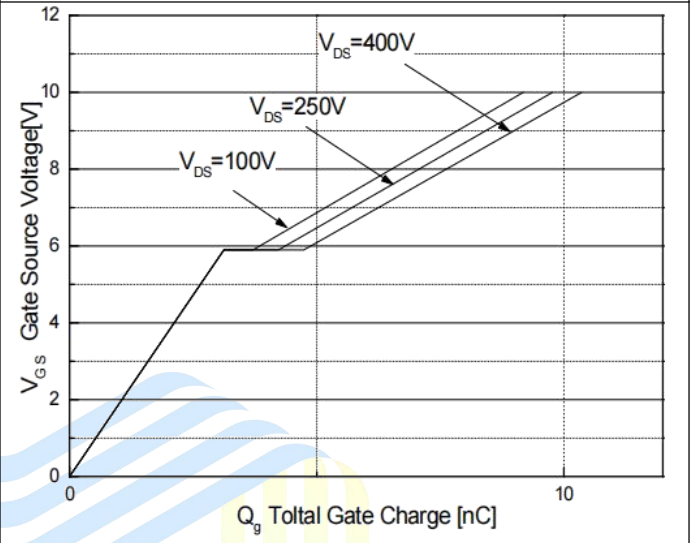
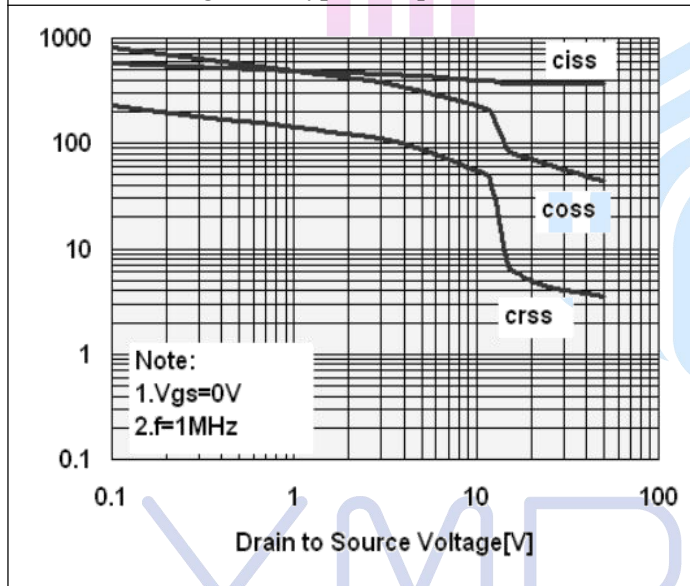
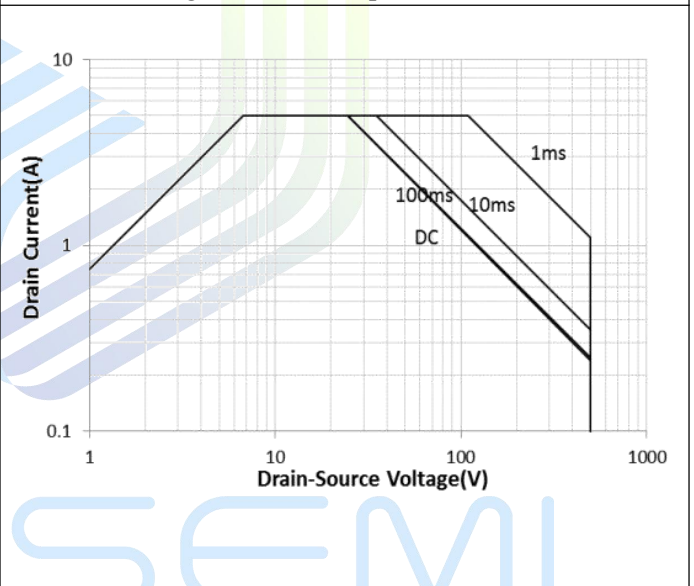
**Electrical Characteristics** ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise specified)

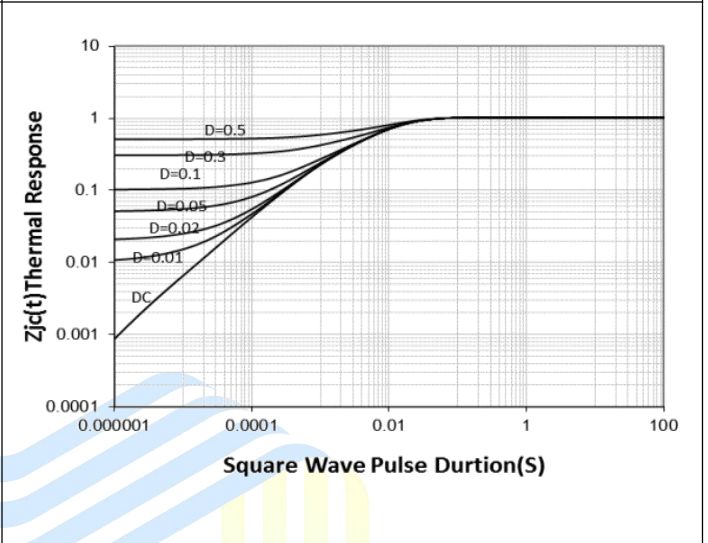
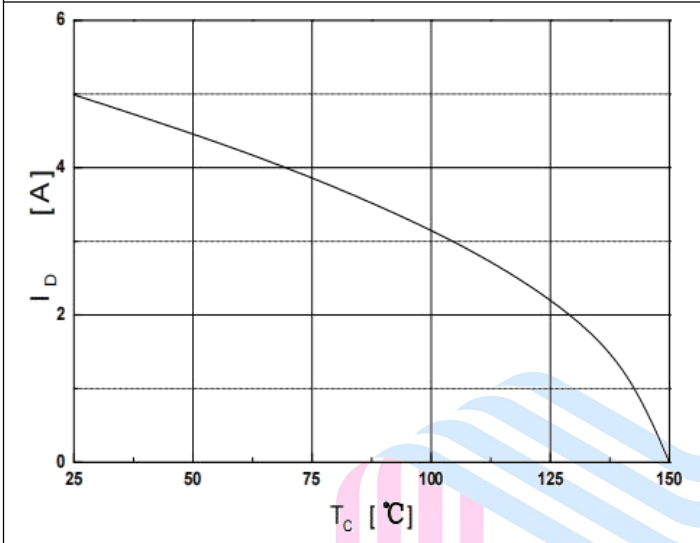
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	500	-	-	V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu A$ referenced to $25^\circ\text{C}$	-	0.5	-	V/ $^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=500V, V_{GS}=0V$ $T_C=25\text{ }^\circ\text{C}$	-	-	10	uA
		$V_{DS}=400V, V_{GS}=0V$ $T_C=125\text{ }^\circ\text{C}$	-	-	100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.5	-	4.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=2.5A$	-	1.25	1.45	$\Omega$
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=40V, I_D=2.5A$	-	3.47	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=25V$	-	370	463	pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$	-	62	78	pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1\text{MHz}$	-	4.3	5.4	pF
<b>Switching Parameters</b> <sup>Note4,5</sup>						
Total Gate Charge	$Q_g$	$V_{DS}=400V$	-	10.3	14.5	nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$	-	3.1	-	
Gate-Drain Charge	$Q_{gd}$	$I_D=5A$	-	4.6	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=250V$ $I_D=5A$ $R_G=25\Omega$	-	19.2	23	ns
Turn-on Rise Time	$t_r$		-	25.3	30	
Turn-off Delay Time	$t_{d(off)}$		-	35.2	42	
Turn-off Fall Time	$t_f$		-	24	29	
<b>Diode Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=5A$	-	-	1.4	V
Reverse recovery time <sup>Note4</sup>	$t_{rr}$	$V_{GS}=0V, I_{SD}=5A$	-	106	-	ns
Reverse recovery charge <sup>Note4</sup>	$Q_{rr}$	$di/dt=100A/\mu s$	-	0.14	-	uC

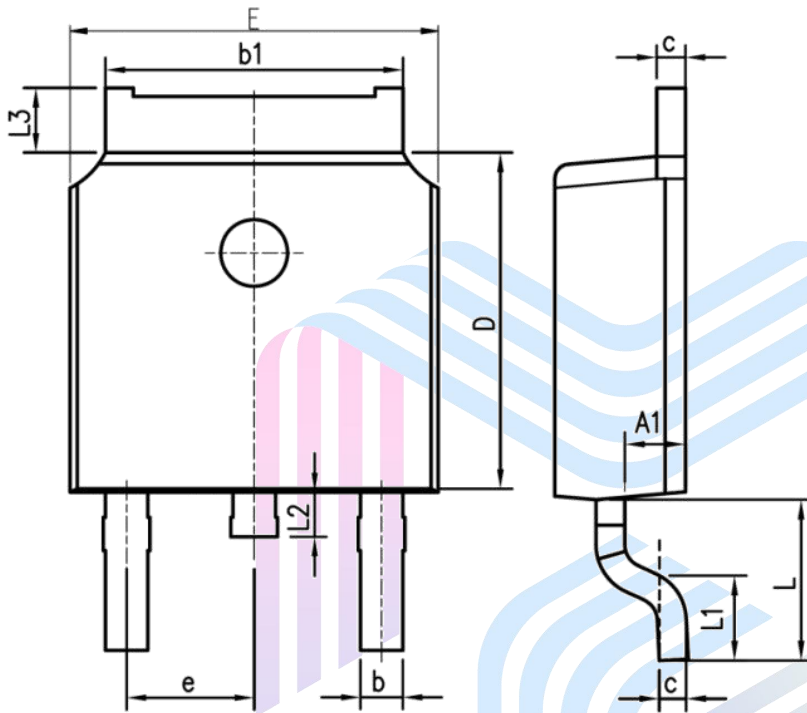
**Notes:**

1. Pulse width limited by maximum junction
2.  $L=10.5\text{mH}, I_{AS}=5A, V_{DD}=50V, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3.  $I_{SD}\leq 5A, di/dt\leq 200A/\mu s, V_{DD}\leq BV_{DSS}$ , Starting  $T_J=25^\circ\text{C}$
4. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
5. Essentially independent of operating temperature

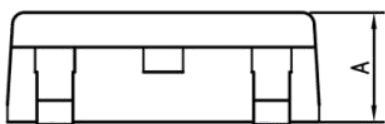
**Typical Performance Characteristics**
**Figure 3: Transfer Characteristics**

**Figure 4: Output Characteristics**

**Figure 5: On-Resistance vs. Drain Current**

**Figure 6: On-Resistance vs. Temperature**


**Figure 7: Body Diode Characteristics**

**Figure 8: Gate Charge**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


**Figure 11: Maximum Drain Current vs. Case Temperature**
**Figure 12: Normalized Maximum Transient Thermal Impedance**


**Mechanical Dimensions:**
**TO-252 Package Information**
**Unit:mm**


SYMBOL	mm	
	MIN	MAX
A	2.10	2.50
A1	0.97	1.17
b	0.63	0.93
b1	5.13	5.53
c	0.40	0.60
D	5.80	6.40
E	6.30	6.90
e	2.286BSC	
L	2.50	3.30
L1	1.20	1.80
L2	0.60	1.00
L3	0.85	1.30



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